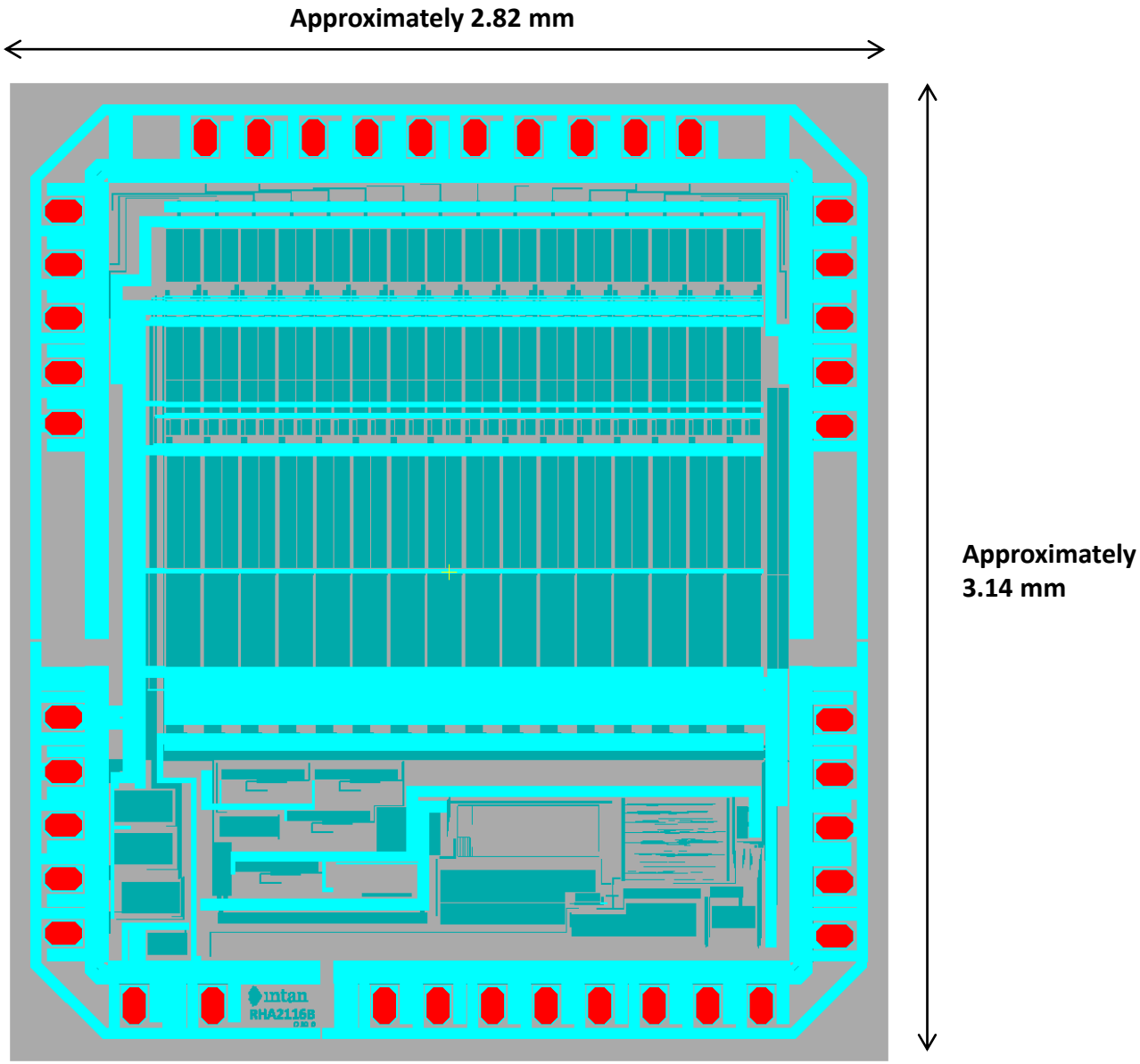
# RHA2116 Bare Die

Gray = approximate outline of die (may vary from die to die due to variations in sawing)

Yellow Cross = center of design (may not coincide precisely with center of die due to variations in sawing)

Blue, Green = top metal layers (highly visible)

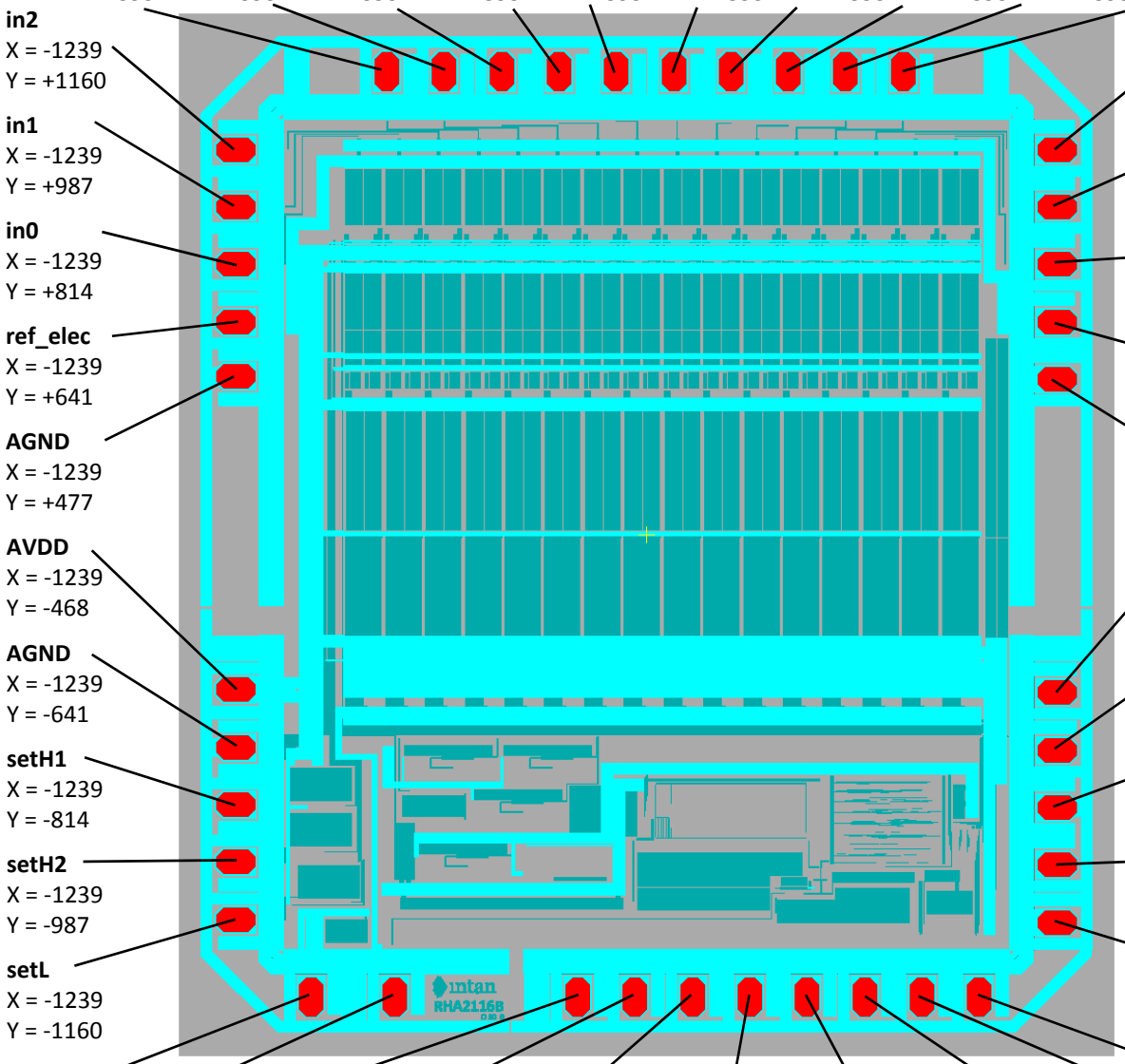
Red = glass openings for bond pads




Each die is 254 µm (10 mils) thick

# RHA2116 Coordinates of Bondpad Centers, Relative to Center of Design

dimensions in microns




**in3**
X = -783
Y = +1395

**in4**
X = -610
Y = +1395

**in5**
X = -437
Y = +1395

**in6**
X = -264
Y = +1395

**in7**
X = -91
Y = +1395

**in8**
X = +82
Y = +1395

**in9**
X = +255
Y = +1395

**in10**
X = +428
Y = +1395

**in11**
X = +601
Y = +1395

**in12**
X = +774
Y = +1395

**in2**
X = -1239
Y = +1160

**in1**
X = -1239
Y = +987

**in0**
X = -1239
Y = +814

**ref_elec**
X = -1239
Y = +641

**AGND**
X = -1239
Y = +477

**AVDD**
X = -1239
Y = -468

**AGND**
X = -1239
Y = -641

**setH1**
X = -1239
Y = -814

**setH2**
X = -1239
Y = -987

**setL**
X = -1239
Y = -1160

**in13**
X = +1239
Y = +1160

**in14**
X = +1239
Y = +987

**in15**
X = +1239
Y = +814

**elec_test**
X = +1239
Y = +641

**VESD**
X = +1239
Y = +468

**conn_all**
X = +1239
Y = -477

**test_en**
X = +1239
Y = -650

**DGND**
X = +1239
Y = -823

**DGND**
X = +1239
Y = -996

**DVDD**
X = +1239
Y = -1169

**nc**
X = -1013
Y = -1395

**MUX_out**
X = -760
Y = -1395

**settle**
X = -207
Y = -1395

**sel0/$\overline{\text{reset}}$**
X = -34
Y = -1395

**sel1/step**
X = +139
Y = -1395

**sel2/sync**
X = +312
Y = -1395

**sel3**
X = +485
Y = -1395

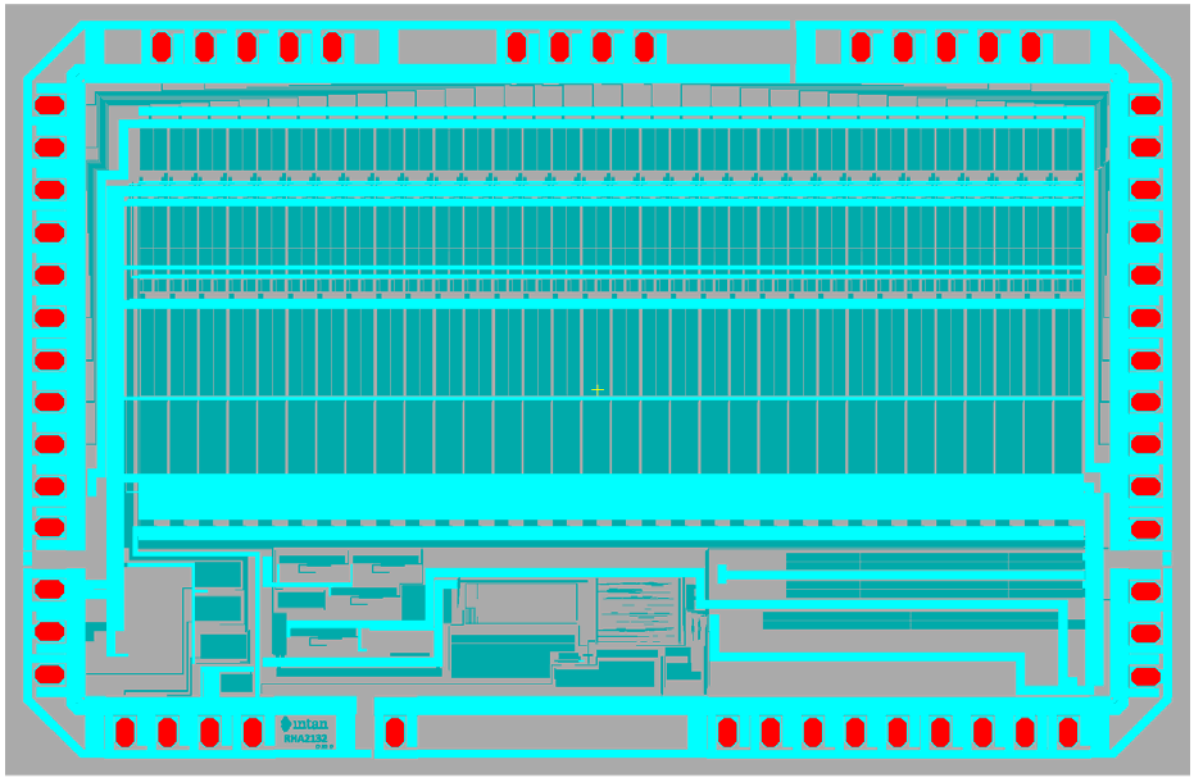
**HiZ_MUX**
X = +658
Y = -1395

**mode**
X = +831
Y = -1395

**nc**
X = +1004
Y = -1395

# RHA2132 Bare Die

Approximately 4.82 mm



Approximately 3.14 mm

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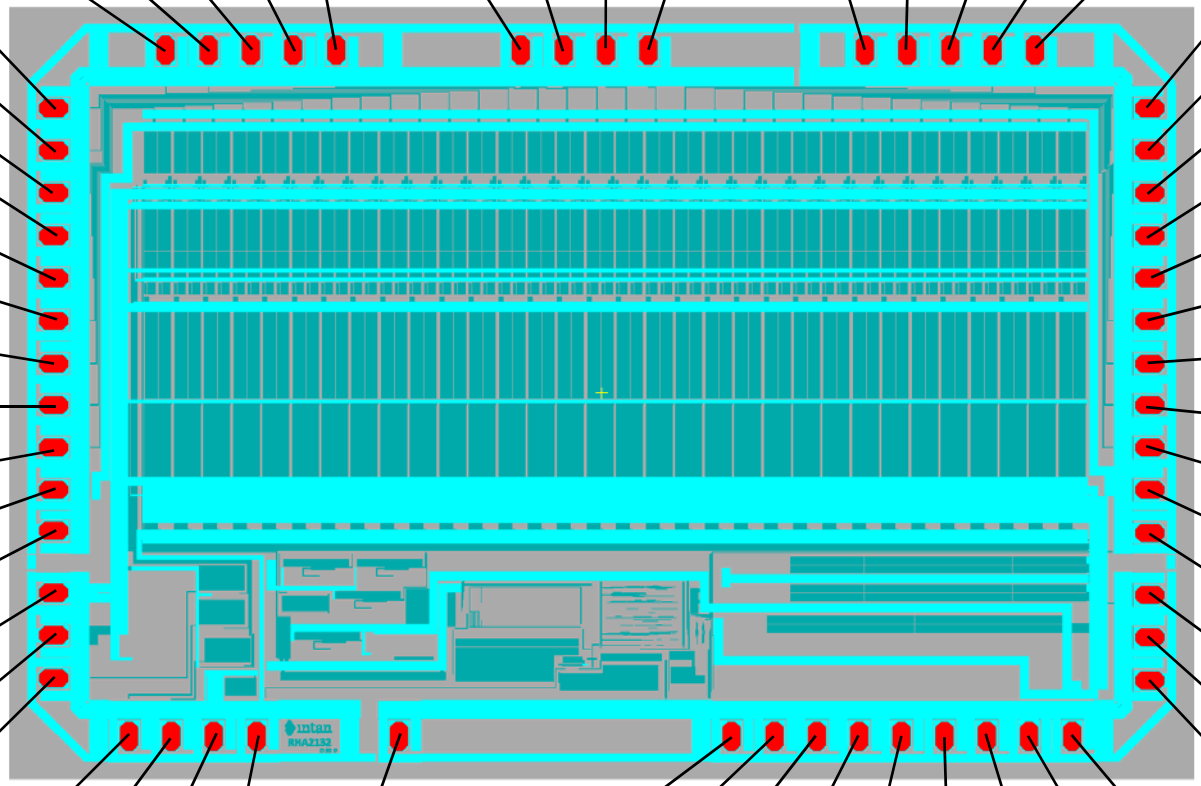
**Red** = glass openings for bond pads

**Each die is 254 µm (10 mils) thick**

# RHA2132 Coordinates of Bondpad Centers, Relative to Center of Design

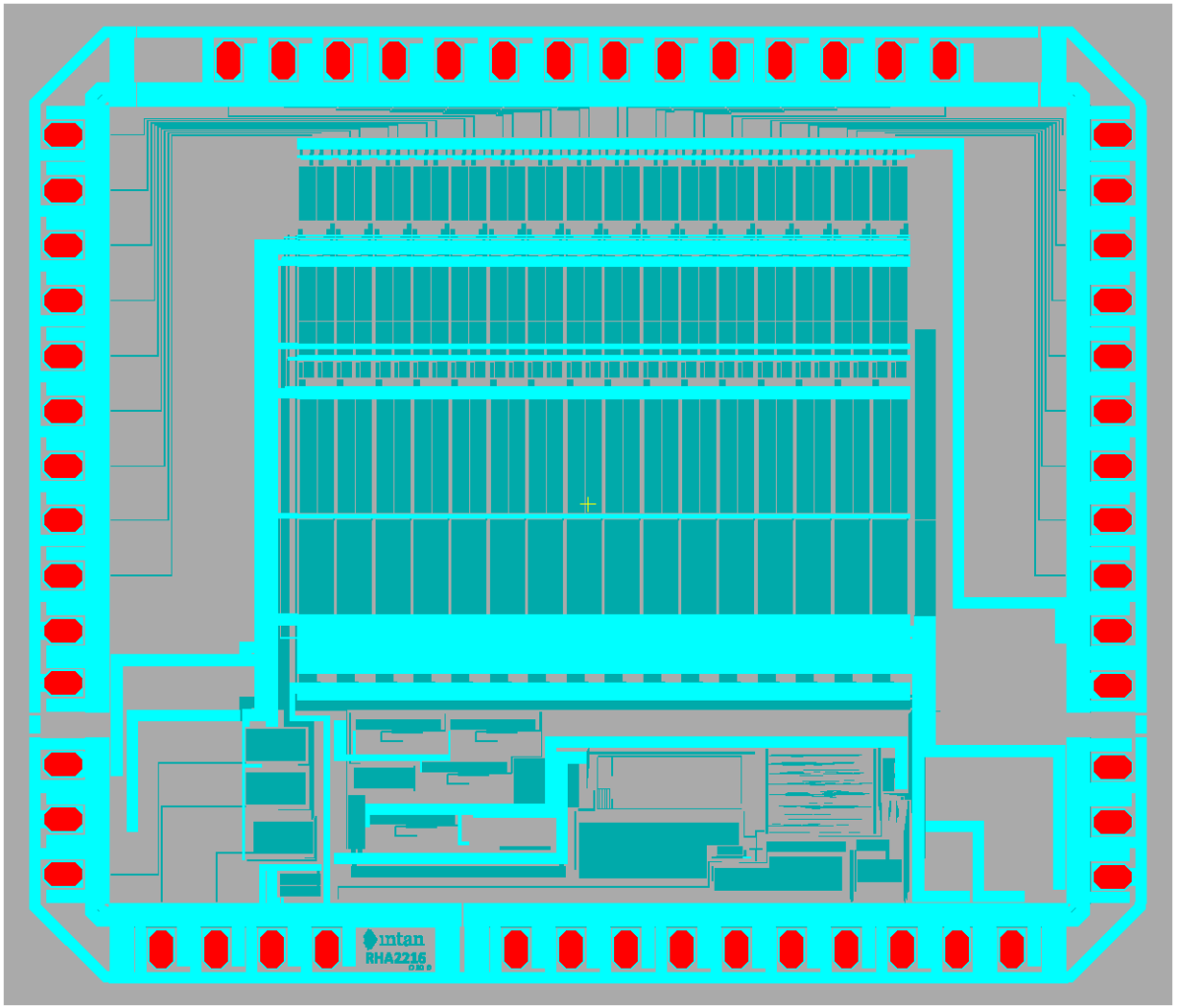
dimensions in microns



| | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| in8 X = -2229 Y = +1160 | in9 X = -1773 Y = +1395 | in10 X = -1600 Y = +1395 | in11 X = -1427 Y = +1395 | in12 X = -1254 Y = +1395 | in13 X = -1081 Y = +1395 | in14 X = -328 Y = +1395 | in15 X = -155 Y = +1395 | in16 X = +18 Y = +1395 | in17 X = +191 Y = +1395 | in18 X = +1072 Y = +1395 | in19 X = +1245 Y = +1395 | in20 X = +1418 Y = +1395 | in21 X = +1591 Y = +1395 | in22 X = +1764 Y = +1395 | in23 X = +2229 Y = +1160 |
| in7 X = -2229 Y = +987 | | | | | | | | | | | | | | | in24 X = +2229 Y = +987 |
| in6 X = -2229 Y = +814 | | | | | | | | | | | | | | | in25 X = +2229 Y = +814 |
| in5 X = -2229 Y = +641 | | | | | | | | | | | | | | | in26 X = +2229 Y = +641 |
| in4 X = -2229 Y = +468 | | | | | | | | | | | | | | | in27 X = +2229 Y = +468 |
| in3 X = -2229 Y = +295 | | | | | | | | | | | | | | | in28 X = +2229 Y = +295 |
| in2 X = -2229 Y = +122 | | | | | | | | | | | | | | | in29 X = +2229 Y = +122 |
| in1 X = -2229 Y = -51 | | | | | | | | | | | | | | | in30 X = +2229 Y = -51 |
| in0 X = -2229 Y = -224 | | | | | | | | | | | | | | | in31 X = +2229 Y = -224 |
| ref_elec X = -2229 Y = -397 | | | | | | | | | | | | | | | elec_test X = +2229 Y = -397 |
| AGND X = -2229 Y = -561 | | | | | | | | | | | | | | | VESD X = +2229 Y = -570 |
| AVDD X = -2229 Y = -814 | | | | | | | | | | | | | | | conn_all X = +2229 Y = -823 |
| AGND X = -2229 Y = -987 | | | | | | | | | | | | | | | test_en X = +2229 Y = -996 |
| setH1 X = -2229 Y = -1160 | setH2 X = -1923 Y = -1395 | setL X = -1750 Y = -1395 | nc X = -1577 Y = -1395 | MUX_out X = -1404 Y = -1395 | settle X = -823 Y = -1395 | sel0/reset X = +530 Y = -1395 | sel1/step X = +703 Y = -1395 | sel2/sync X = +876 Y = -1395 | sel3 X = +1049 Y = -1395 | sel4 X = +1222 Y = -1395 | mode X = +1395 Y = -1395 | nc X = +1568 Y = -1395 | DVDD X = +1741 Y = -1395 | DGND X = +1914 Y = -1395 | DGND X = +2229 Y = -1169 |

# RHA2216 Bare Die

Approximately 3.66 mm




Approximately 3.14 mm

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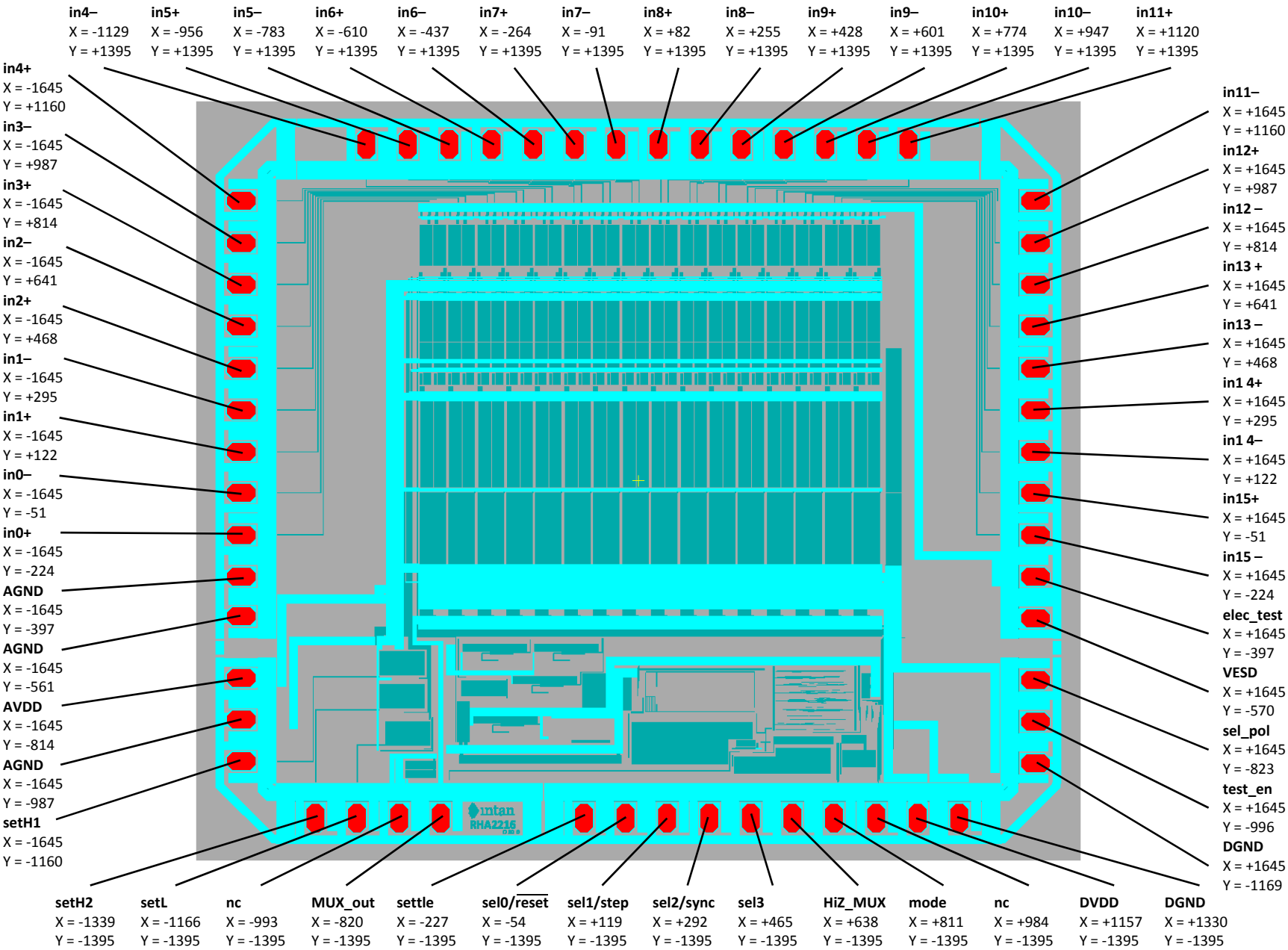
**Each die is 254 µm (10 mils) thick**

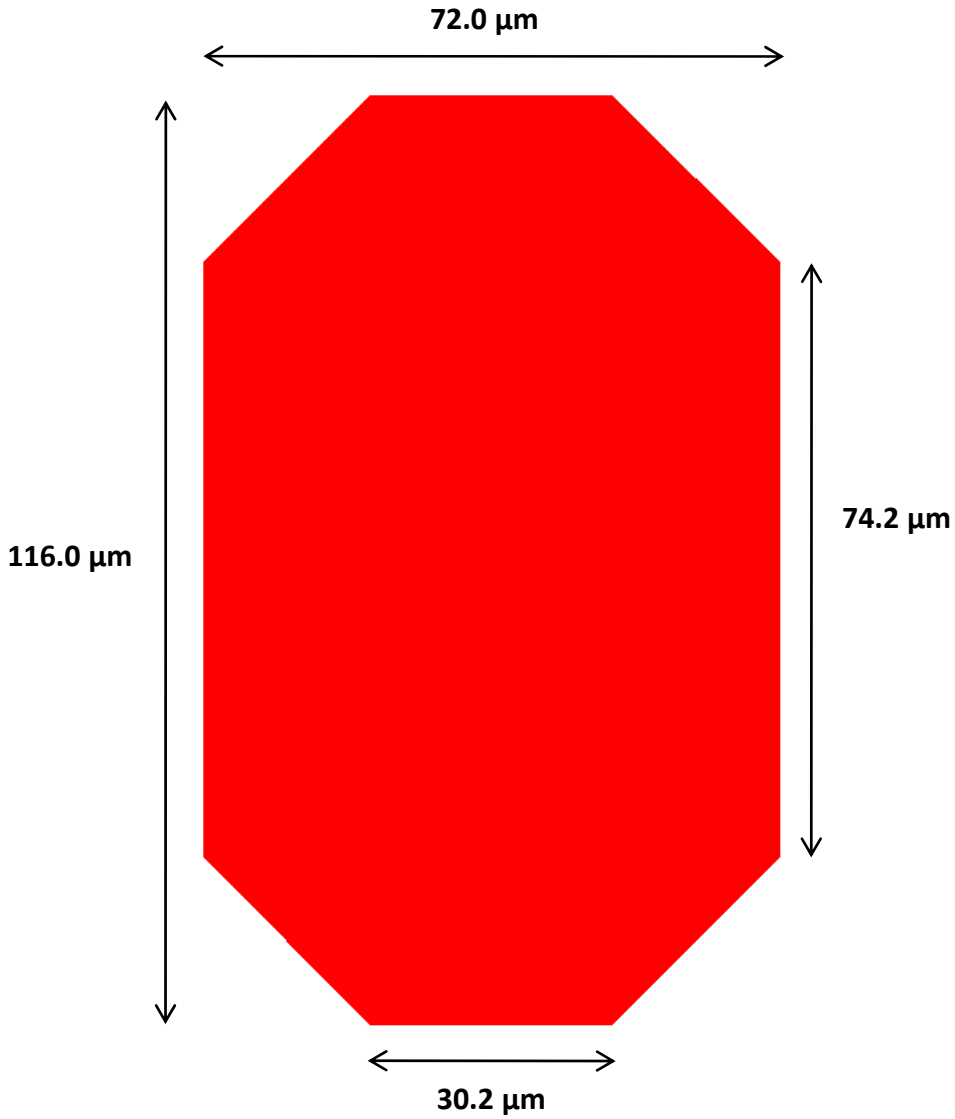
# RHA2216 Coordinates of Bondpad Centers, Relative to Center of Design

dimensions in microns



# RHA2000-Series Bondpad Dimensions

Bondpad metal: Aluminum




Minimum bond pad pitch (center to center) on RHA2000-series chips = 173 µm